



Material Content Data Sheet



Sales Product Name				IPD034N06N3 G		Issued		9. January 2019	
MA#				MA002510244					
Package				PG-TO252-3-11		Weight*		372.74 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.152	1.38	1.38	13822	13822	
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		173		
	non noble metal	iron	7439-89-6	0.215	0.06		578		
	non noble metal	copper	7440-50-8	215.017	57.70	57.78	576856	577607	
	non noble metal	aluminium	7429-90-5	4.874	1.31	1.31	13076	13076	
wire	non noble metal	aluminium	7429-90-5	4.874	1.31	1.31	13076	13076	
encapsulation	organic material	carbon black	1333-86-4	1.204	0.32		3230		
	plastics	epoxy resin	-	21.068	5.65		56521		
	inorganic material	silicondioxide	60676-86-0	98.115	26.32	32.29	263227	322978	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10034	10034	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	244	245	
solder	non noble metal	tin	7440-31-5	0.080	0.02		214		
	noble metal	silver	7440-22-4	0.100	0.03		268		
	non noble metal	lead	7439-92-1	3.817	1.02	1.07	10239	10721	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15		
	non noble metal	iron	7439-89-6	0.019	0.01		52		
	non noble metal	copper	7440-50-8	19.177	5.14	5.15	51450	51517	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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